December		
Customer Contact: PCN Manager Change Type: □ Assembly Site □ Assembly Process □ Assembly Materials □ Assembly Materials □ Assembly Materials □ Part number change □ Wafer Bump Material □ Assembly Materials □ Part number change □ Wafer Bump Process □ Wafer Bump Process □ Wafer Bump Process □ Wafer Fab Site □ Packing/Shipping/Labeling □ Test Site □ Packing/Shipping/Labeling □ Test Process □ Wafer Fab Materials □ Wafer Fab Process Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS INSTRUMENTS TPS3813K33-Q1, TPS3813I50-Q1 SPRS288G - MAY 2008 - REVISED OCTOBER 2019 Changes from Revision F (December 2016) to Revision G Page Updated text for device conditions on start-up		
Change Type: □ Assembly Site □ Design □ Wafer Bump Site □ Assembly Process □ Data Sheet □ Wafer Bump Material □ Assembly Materials □ Part number change □ Wafer Bump Process □ Mechanical Specification □ Test Site □ Wafer Fab Site □ Packing/Shipping/Labeling □ Test Process □ Wafer Fab Materials □ Wafer Fab Process ■ Wafer Fab Process Notification Details Description of Change: □ Wafer Fab Process Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TPS3813K33-Q1, TPS3813I50-Q1 SPRS288G - MAY 2008 - REVISED OCTOBER 2019 Changes from Revision F (December 2016) to Revision G Page • Updated text for device conditions on start-up. 7		
Assembly Site Design Wafer Bump Site Assembly Process Data Sheet Wafer Bump Material Assembly Materials Part number change Wafer Bump Process Mechanical Specification Test Site Wafer Fab Site Packing/Shipping/Labeling Test Process Wafer Fab Materials Wafer Fab Process Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS INSTRUMENTS TPS3813K33-Q1, TPS3813I50-Q1 SPRS288G - MAY 2008 - REVISED OCTOBER 2019 Changes from Revision F (December 2016) to Revision G Page Updated text for device conditions on start-up. 7		
Assembly Process Assembly Materials Part number change Wafer Bump Process Mechanical Specification Test Site Packing/Shipping/Labeling Test Process Wafer Fab Materials Wafer Fab Materials Wafer Fab Process Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS INSTRUMENTS TPS3813K33-Q1, TPS3813I50-Q1 SPRS288G - MAY 2008 - REVISED OCTOBER 2019 Changes from Revision F (December 2016) to Revision G Page Updated text for device conditions on start-up. 7		
Assembly Materials Part number change Wafer Bump Process Mechanical Specification Test Site Wafer Fab Site Packing/Shipping/Labeling Test Process Wafer Fab Materials Wafer Fab Process Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS INSTRUMENTS TPS3813K33-Q1, TPS3813I50-Q1 SPRS288G - MAY 2008 - REVISED OCTOBER 2019 Changes from Revision F (December 2016) to Revision G Page Updated text for device conditions on start-up. 7		
Mechanical Specification Test Site Wafer Fab Site Packing/Shipping/Labeling Test Process Wafer Fab Materials Wafer Fab Process Wafer Fab Materials Wafer Fab Process Wa		
Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.		
Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS TPS3813K33-Q1, TPS3813I50-Q1 SPRS288G - MAY 2008 - REVISED OCTOBER 2019 Changes from Revision F (December 2016) to Revision G Page Updated text for device conditions on start-up.		
Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. Texas Instruments Ins		
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. Texas Instruments Texas Instruments Instr		
The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS TPS3813K33-Q1, TPS3813I50-Q1 SPRS288G - MAY 2008 - REVISED OCTOBER 2019 Changes from Revision F (December 2016) to Revision G Page Updated text for device conditions on start-up. 7		
The following change history provides further details. TEXAS INSTRUMENTS TPS3813K33-Q1, TPS3813I50-Q1 SPRS288G - MAY 2008-REVISED OCTOBER 2019 Changes from Revision F (December 2016) to Revision G Page Updated text for device conditions on start-up. 7		
TEXAS INSTRUMENTS TPS3813K33-Q1, TPS3813I50-Q1 SPRS288G - MAY 2008-REVISED OCTOBER 2019 Changes from Revision F (December 2016) to Revision G Page Updated text for device conditions on start-up. 7		
Changes from Revision F (December 2016) to Revision G Updated text for device conditions on start-up.		
Changes from Revision F (December 2016) to Revision G Updated text for device conditions on start-up.		
Changes from Revision F (December 2016) to Revision G Updated text for device conditions on start-up.		
Updated text for device conditions on start-up		
Updated text for device conditions on start-up		
·		
Added information to further clarify shaded areas in the Upper and Lower Boundary Visualization		
The datasheet number will be changing.		
Device Family Change From: Change To:		
TPS3813K33-Q1, TPS3813I50-Q1		
These changes may be reviewed at the datasheet links provided.		
http://www.ti.com/product/TPS3813K33-Q1		
Reason for Change:		
To accurately reflect device characteristics.		
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):		
No anticipated impact. This is a specification change announcement only. There are no changes		
to the actual device.		
to the actual device.		
to the actual device. Changes to product identification resulting from this PCN:		
Changes to product identification resulting from this PCN:		

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN www admin_team@list.ti.com

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.